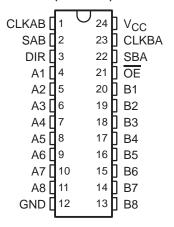
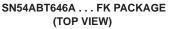
SCBS069H - JULY 1991 - REVISED MAY 2004

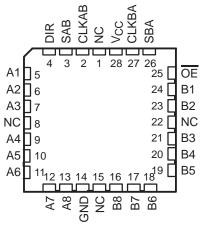
- Typical V<sub>OLP</sub> (Output Ground Bounce) <1 V at  $V_{CC} = 5$  V,  $T_A = 25^{\circ}$ C
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Ioff Supports Partial-Power-Down Mode Operation

SN54ABT646A...JT OR W PACKAGE SN74ABT646A...DB, DGV, DW, NS, NT, OR PW PACKAGE (TOP VIEW)



- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- **ESD Protection Exceeds JESD 22** 
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)





NC - No internal connection

## description/ordering information

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT646A devices.

#### ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – NT	Tube	SN74ABT646ANT	SN74ABT646ANT
	2010 DW	Tube	SN74ABT646ADW	ADT040A
	SOIC - DW	Tape and reel	SN74ABT646ADWR	ABT646A
4000 / 0500	SOP - NS	Tape and reel	SN74ABT646ANSR	ABT646A
-40°C to 85°C	SSOP - DB	Tape and reel	SN74ABT646ADBR	AB646A
	TOOOD DW	Tube	SN74ABT646APW	AD040A
	TSSOP – PW	Tape and reel	SN74ABT646APWR	AB646A
	TVSOP - DGV	Tape and reel	SN74ABT646ADGVR	AB646A
	CDIP – JT	Tube	SNJ54ABT646AJT	SNJ54ABT646AJT
–55°C to 125°C	CFP – W	Tube	SNJ54ABT646AW	SNJ54ABT646AW
	LCCC - FK	Tube	SNJ54ABT646AFK	SNJ54ABT646AFK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCBS069H - JULY 1991 - REVISED MAY 2004

### description/ordering information(continued)

Output-enable  $(\overline{OE})$  and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either register or in both.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus receives data when  $\overline{OE}$  is low. In the isolation mode ( $\overline{OE}$  high), A data can be stored in one register and/or B data can be stored in the other register.

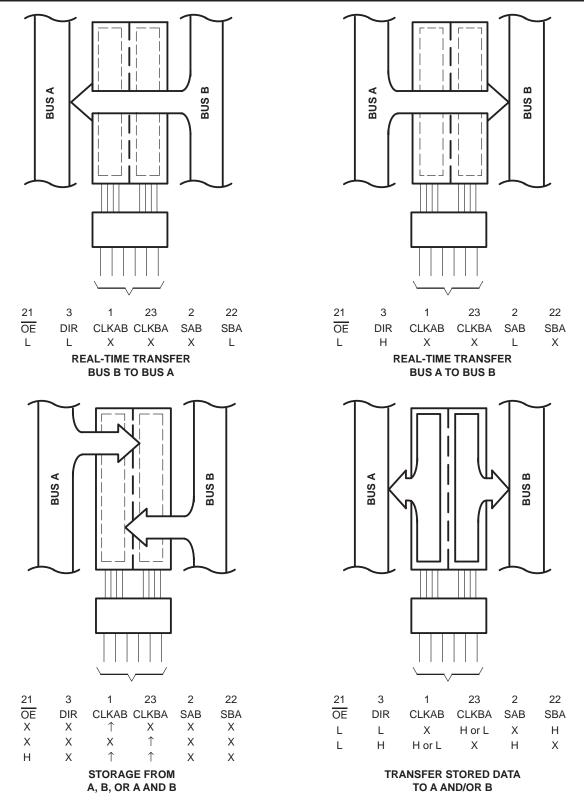
When an output function is disabled, the input function still is enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

These devices are fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



SCBS069H - JULY 1991 - REVISED MAY 2004



Pin numbers shown are for the DB, DGV, DW, JT, NS, NT, PW, and W packages.

Figure 1. Bus-Management Functions

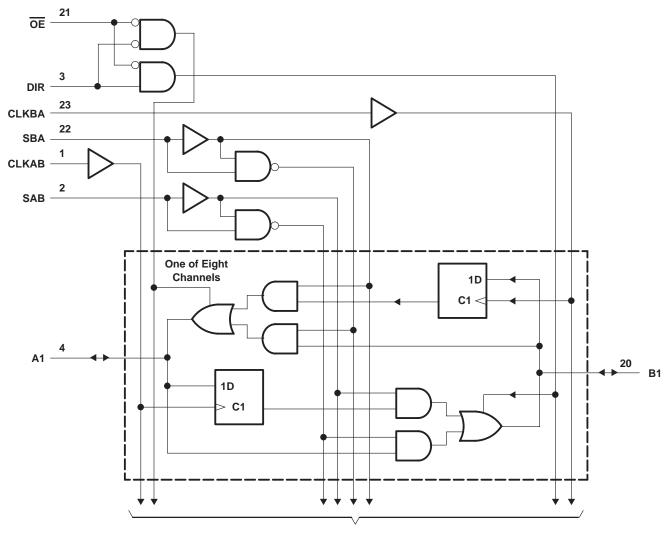


#### **FUNCTION TABLE**

		INP	UTS			DATA	A I/Os	
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Χ	Х	Х	Input	Unspecified <sup>†</sup>	Store A, B unspecified <sup>†</sup>
Х	X	X	$\uparrow$	X	Χ	Unspecified <sup>†</sup>	Input	Store B, A unspecified <sup>†</sup>
Н	Х	1	$\uparrow$	Х	Х	Input	Input	Store A and B data
Н	X	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Χ	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus

<sup>†</sup> The data-output functions can be enabled or disabled by various signals at  $\overline{OE}$  and DIR. Data-input functions always are enabled, i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

## logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for the DB, DGV, DW, JT, NS, NT, PW, and W packages.



SCBS069H - JULY 1991 - REVISED MAY 2004

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT646A	96 mA
SN74ABT646A	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DB package	63°C/W
(see Note 2): DGV package	86°C/W
(see Note 2): DW package	46°C/W
(see Note 2): NS package	65°C/W
(see Note 3): NT package	67°C/W
(see Note 2): PW package	88°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-3.

## recommended operating conditions (see Note 4)

		SN54AB	T646A	SN74AB	T646A	LINUT
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
VIL	Low-level input voltage		0.8		8.0	V
VI	Input voltage	0	VCC	0	VCC	V
loh	High-level output current		-24		-32	mA
loL	Low-level output current		48		64	mA
Δt/Δν	Input transition rise or fall rate		5		5	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCBS069H - JULY 1991 - REVISED MAY 2004

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54AB	T646A	SN74AB	T646A	
PA	ARAMETER	TEST COI	NDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT
٧ıK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
.,		V <sub>CC</sub> = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V 45V	$I_{OH} = -24 \text{ mA}$	2			2				V
		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -32 mA	2*					2		
\/ - ·		V 45V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V
V <sub>hys</sub>					100						mV
1.	Control inputs	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND				±1		±1		±1	^
II	A or B ports	VCC = 5.5 V, VI =	ACC or GMD			±100		±100		±100	μΑ
lozH <sup>‡</sup>	‡	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			10§		10§		10§	μΑ
l <sub>OZL</sub> ‡		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-10§		-10§		-10§	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V <sub>C</sub> C = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
Io¶		V <sub>C</sub> C = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		V <sub>CC</sub> = 5.5 V,	Outputs high			250		250		250	μΑ
Icc		$I_{O} = 0$ ,	Outputs low			30		30		30	mA
	$V_I = V_{CC}$ or GND		Outputs disabled			250		250		250	μΑ
∆lcc <sup>#</sup>	<i>‡</i>	V <sub>CC</sub> = 5.5 V, One Other inputs at V <sub>C</sub>	input at 3.4 V, C or GND			1.5		1.5		1.5	mA
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V		7						pF	
C <sub>io</sub>	A or B ports	$V_0 = 2.5 \text{ V or } 0.5$	V		12						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			SN54AE	3T646A		
		V <sub>CC</sub> =	= 5 V, 25°C	MIN	MAX	UNIT
		MIN MAX				
fclock	Clock frequency		125		125	MHz
t <sub>W</sub>	Pulse duration, CLK high or low	4		4		ns
t <sub>su</sub>	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3.5		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	1.5		1.5		ns



<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> The parameters IOZH and IOZL include the input leakage current.

<sup>§</sup> This data-sheet limit may vary among suppliers.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>#</sup>This is the increase in supply current for each input that is at the specified TTL voltage level, rather than VCC or GND.

SCBS069H - JULY 1991 - REVISED MAY 2004

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			SN74AI	3T646A		
		V <sub>CC</sub> =	= 5 V, 25°C	MIN	MAX	UNIT
		MIN	MAX			
fclock	Clock frequency		125		125	MHz
t <sub>W</sub>	Pulse duration, CLK high or low	4		4		ns
t <sub>su</sub>	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

				SN5	4ABT64	I6A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		MIN	MAX	UNIT
			MIN	TYP	MAX			
f <sub>max</sub>			125			125		MHz
<sup>t</sup> PLH	CLIVDA au CLIVAD	A av D	2.2	4	5.1	2.2	6.7	
t <sub>PHL</sub>	CLKBA or CLKAB	A or B	1.7	4	5.1	1.2	6.7	ns
<sup>t</sup> PLH	A - :: B	D A	1.5	3	4.3	1.5	5	
t <sub>PHL</sub>	A or B	B or A	1.5	3.3	4.6	1.5	5.6	ns
<sup>t</sup> PLH	040 004	D on A	1.5	4	5.7	1.5	7.8	
t <sub>PHL</sub>	SAB or SBA†	B or A	1.5	3.6	4.9	1.5	6.2	ns
<sup>t</sup> PZH	<del></del> <del>OE</del>	A D	1.5	4.3	5.3	1.5	7	
<sup>t</sup> PZL	OE OE	A or B	3	5.8	8	3	10.5	ns
<sup>t</sup> PHZ	ŌĒ	A D	1.5	3.5	5.8	1	7.3	
t <sub>PLZ</sub>	OE OE	A or B	1.5	3	4	1.5	5.7	ns
<sup>t</sup> PZH	DID	A D	1.5	4.5	5.7	1.5	7.3	
tPZL	DIR	A or B	2.5	6.5	9	2.5	11	ns
t <sub>PHZ</sub>	DIR	A or B	1.5	3.8	6.5	1	9	nc
<sup>t</sup> PLZ	DIK	AUIB	1.5	3.8	4.7	1.2	6.7	ns

<sup>†</sup>These parameters are measured with the internal output state of the storage register opposite that of the bus input.

SCBS069H - JULY 1991 - REVISED MAY 2004

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

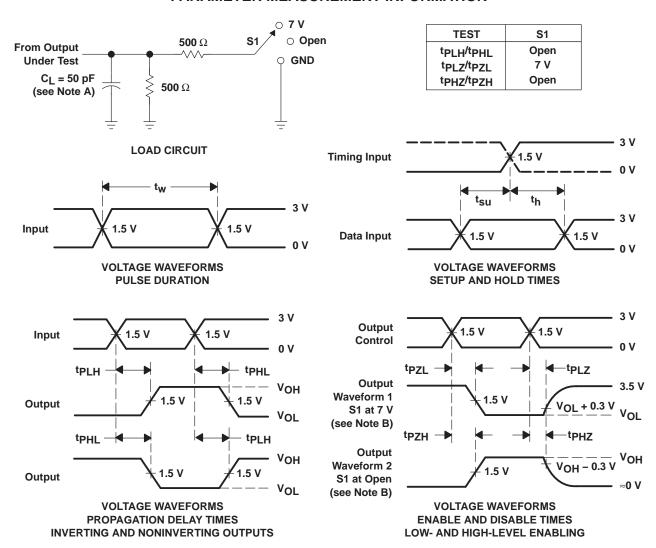
				SN7	4ABT64	l6A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		MIN	MAX	UNIT
			MIN	TYP	MAX			
f <sub>max</sub>			125			125		MHz
t <sub>PLH</sub>	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	5.6	20
t <sub>PHL</sub>	CLKBA OF CLKAB	A OF B	1.7	4	5.1	1.7	5.6	ns
t <sub>PLH</sub>	A an D	D A	1.5	3	4.3	1.5	4.8	
t <sub>PHL</sub>	A or B	B or A	1.5	3.3	4.6	1.5	5.4	ns
t <sub>PLH</sub>	SAB or SBA†	D A	1.5	4	5.1	1.5	6.5	
t <sub>PHL</sub>	SAR OL SRVI	B or A	1.5	3.6	4.9	1.5	5.9	ns
<sup>t</sup> PZH	ŌĒ	A D	1.5	4.3	5.3	1.5	6.3	
t <sub>PZL</sub>	OE	A or B	3	5.8	7.4	3	8.8	ns
<sup>t</sup> PHZ	ŌĒ	A on D	1.5	3.5	4.5	1.5	5	
t <sub>PLZ</sub>	OE	A or B	1.5	3	4	1.5	4.5	ns
<sup>t</sup> PZH	DID	A on D	1.5	4.5	5.7	1.5	6.7	
t <sub>PZL</sub>	DIR	A or B	2.5	6.5	9	2.5	9.5	ns
<sup>t</sup> PHZ	DIR	A or B	1.5	3.8	5	1.5	5.7	ns
t <sub>PLZ</sub>	DIK	AUID	1.5	3.8	4.7	1.5	6	115

<sup>†</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.



SCBS069H - JULY 1991 - REVISED MAY 2004

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms





6-Feb-2020

### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9457702Q3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9457702Q3A SNJ54ABT 646AFK	Samples
5962-9457702QLA	ACTIVE	CDIP	JT	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9457702QL A SNJ54ABT646AJT	Samples
SN74ABT646ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB646A	Samples
SN74ABT646ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT646A	Samples
SN74ABT646ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT646A	Samples
SN74ABT646ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT646A	Samples
SN74ABT646ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT646A	Samples
SN74ABT646APW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB646A	Samples
SNJ54ABT646AFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9457702Q3A SNJ54ABT 646AFK	Samples
SNJ54ABT646AJT	ACTIVE	CDIP	JT	24	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9457702QL A SNJ54ABT646AJT	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.



## PACKAGE OPTION ADDENDUM

6-Feb-2020

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54ABT646A, SN74ABT646A:

Catalog: SN74ABT646A

www.ti.com

Military: SN54ABT646A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 14-Feb-2019

## TAPE AND REEL INFORMATION





_	_	
		3
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT646ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT646ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT646ANSR	SO	NS	24	2000	330.0	24.4	8.3	15.4	2.6	12.0	24.0	Q1

www.ti.com 14-Feb-2019

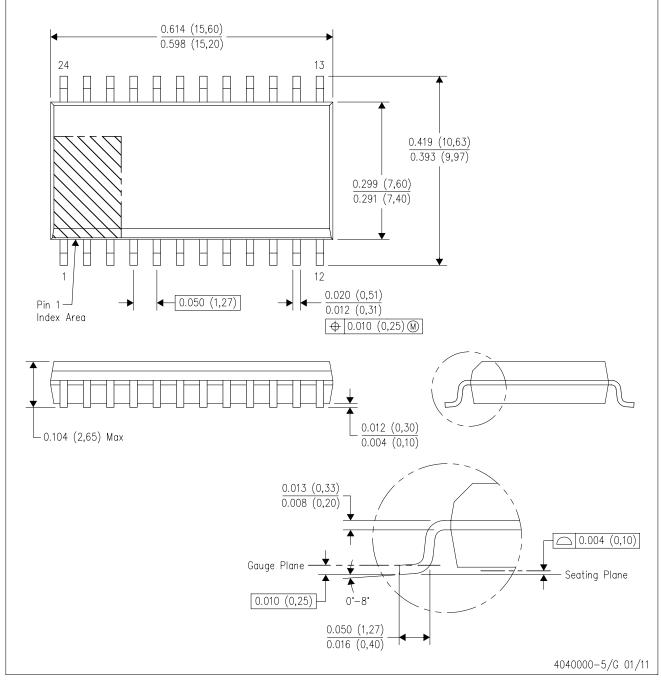


\*All dimensions are nominal

7 till difficilities die Freshmilds							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT646ADBR	SSOP	DB	24	2000	367.0	367.0	38.0
SN74ABT646ADWR	SOIC	DW	24	2000	350.0	350.0	43.0
SN74ABT646ANSR	SO	NS	24	2000	367.0	367.0	45.0

DW (R-PDSO-G24)

# PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

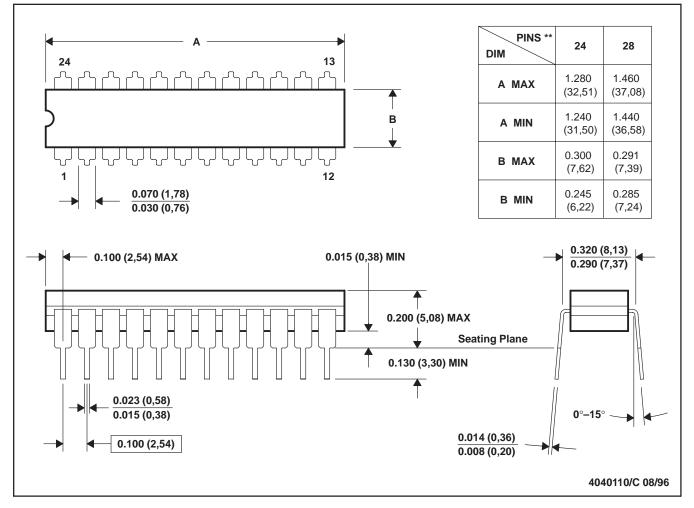
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

### JT (R-GDIP-T\*\*)

#### 24 LEADS SHOWN

### **CERAMIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



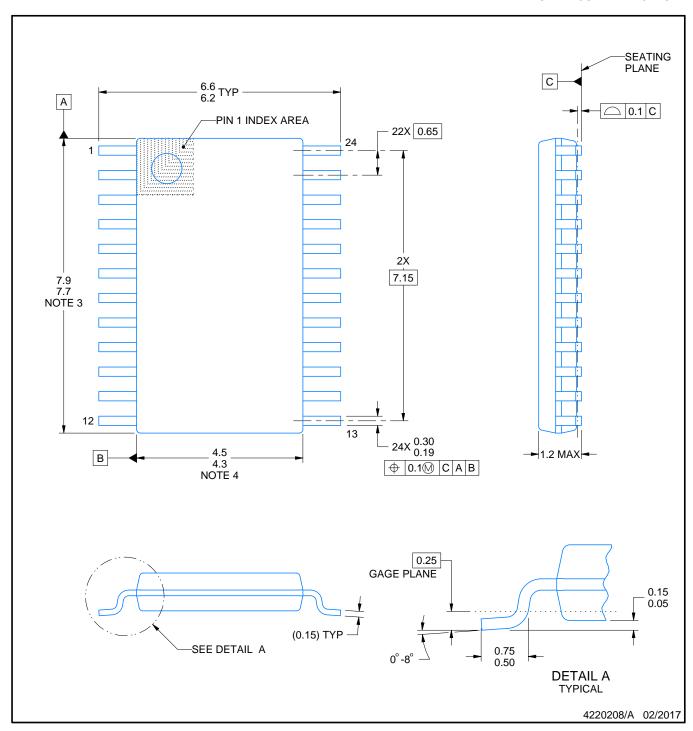
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004





SMALL OUTLINE PACKAGE



#### NOTES:

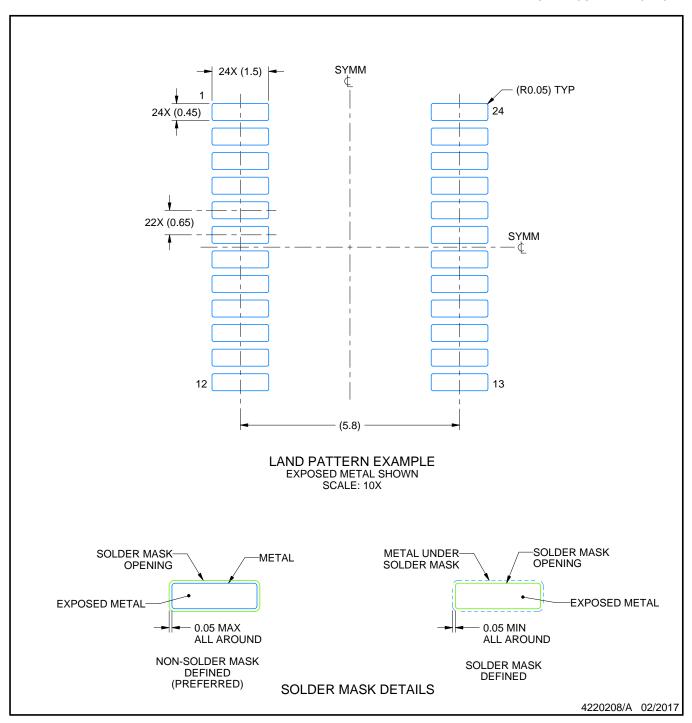
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



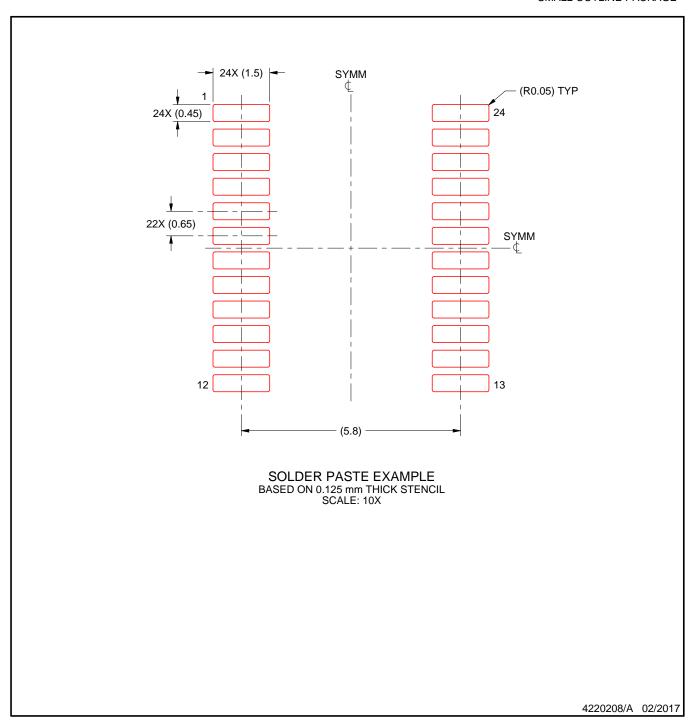
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Tl's products are provided subject to Tl's Terms of Sale (<a href="www.ti.com/legal/termsofsale.html">www.ti.com/legal/termsofsale.html</a>) or other applicable terms available either on ti.com or provided in conjunction with such Tl products. Tl's provision of these resources does not expand or otherwise alter Tl's applicable warranties or warranty disclaimers for Tl products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated